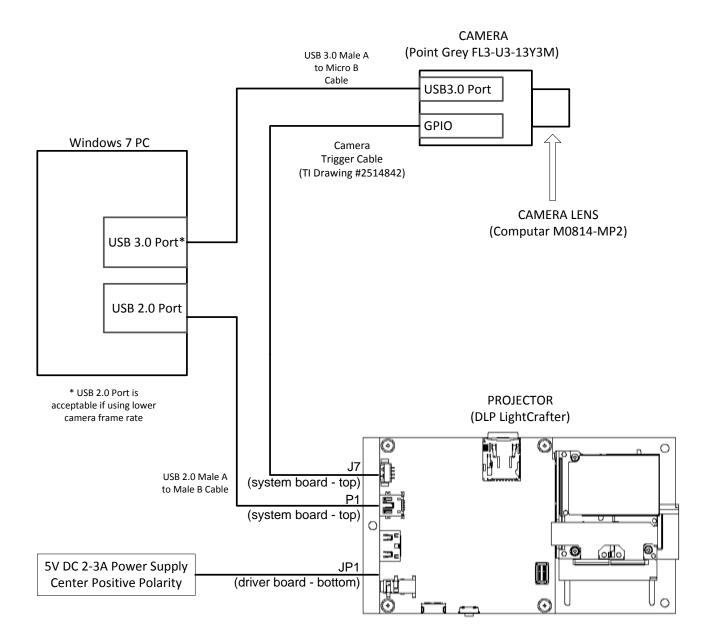
REVISIONS								
REV	DESCRIPTION	DATE	APPROVED					
А	Initial Release	9/30/2015						

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		DWN/CHK	DATE 9/21/2015	TIDA-00361: Portable Point			
		SYS ENGR		Cloud Generation For 3D Scanning			
	0314CP	MANU		using DLP® Technology			
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TIDA-00361: Portable Point Cloud Generation for 3D Scanning using DLP Technology Schematic



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